

Features

- 3535 IR LED
- ROHS and REACH Compliant
- Vertical Patent Free Chip
- ESD 2KV

Applications

- IP Cam
- Security
- Industrial facility applications

Description

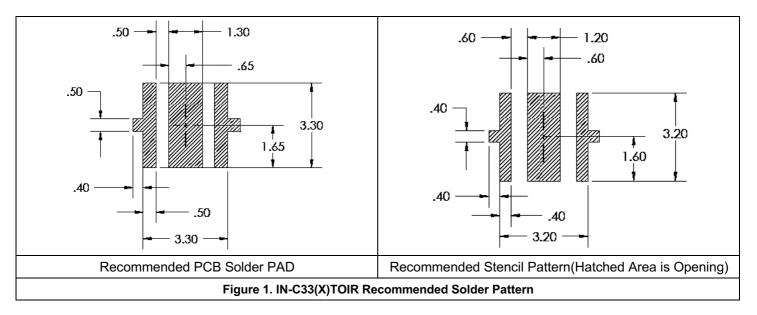
The IN-C33(X)TOIR is a high-power IR LED. It is a SMD type LED which can be used in various applications.



Outline(mm)									
30D	60D	120D	90D						
3.5x3.5x3.38	3.5x3.5x2.8	3.5x3.5x2.0	3.5x3.5x2.34						
IN-C33ATOIR	IN-C33BTOIR	IN-C33CTOIR	IN-C33ETOIR						

Recommended Solder Pattern

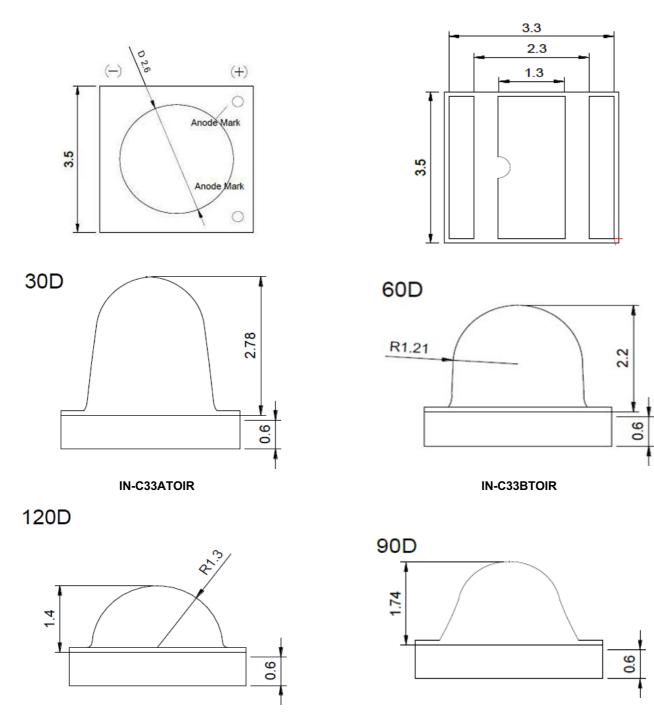
(Suggest Stencil t=0.12 mm)





Package Dimensions

(All dimensions are in mm, tolerance is ±0.13mm)



IN-C33ETOIR



IN-C33CTOIR



Absolute Maximum Rating at 25°C (Note 1)

Product	I _F (mA) max	I _{FP} * (mA)	V _R (V)	l _R (μA) max	T _j (°C)	T₅⊤ (°C)	Rth (°C/W)	Soldering Temp. T _{sol} (°C)
IN-C33ATOIR IN-C33BTOIR IN-C33CTOIR IN-C33ETOIR	1000	1200	-5	10	125 ºC	-40°C~+100°C	10	260 °C

Notes

1. Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

2. When driving at maximum current the Tj must be kept below 125° C

Electrical Characteristics T_A = 25°C (Note 1)

	V _F (V)@1000mA			Beam Angle				
Product	min	typ.	max	IN-C33ATOIR	IN-C33BTOIR	IN-C33CTOIR	IN-C33ETOIR	
IN-C33ATOIR IN-C33BTOIR IN-C33CTOIR IN-C33ETOIR	1.4		2.6	30	60	120	90	

Notes

- 1. Performance guaranteed only under conditions listed in above tables.
- 2. Viewing angle($2\theta 1/2$) ± 10°
- 3. Detail binning information on page 5.

ESD Precaution

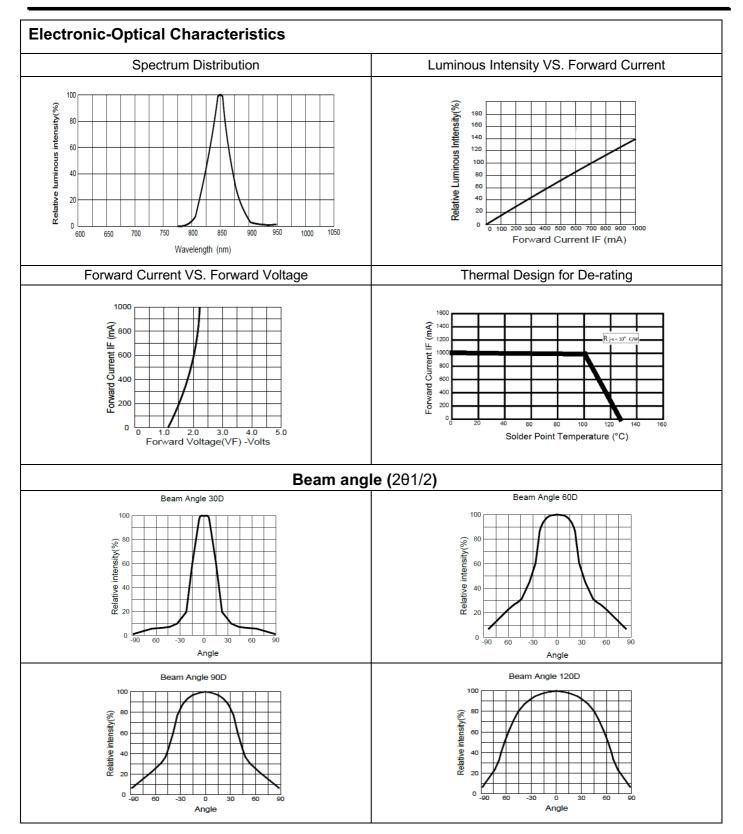




The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).





Notes:

Viewing angle(201/2) ± 10°



Ordering Information

Orderable	Peak Wavelength	Radiometric Power (mW) @1000mA			Forward V		
Part Number	(nm)	Group	Min	Max	Min	Max	Angle
	940.950	А	450	500	1.6	1.8	30°
	840-850	В	500	550	1.8	2.0	30°
IN-C33ATOIR	850-860	С	550	600	2.0	2.2	30°
	000-000	D	600	650	2.2	2.4	30°
	840-850	А	450	500	1.6	1.8	60°
IN-C33BTOIR	040-050	В	500	550	1.8	2.0	60°
IN-C33BTOR	850-860	С	550	600	2.0	2.2	60°
		D	600	650	2.2	2.4	60°
	840-850	А	450	500	1.6	1.8	90°
IN-C33ETOIR	040-000	В	500	550	1.8	2.0	90°
IN-C33ETOR	850-860	С	550	600	2.0	2.2	90°
	000-000	D	600	650	2.2	2.4	90°
	840-850	А	450	500	1.6	1.8	120°
	040-000	В	500	550	1.8	2.0	120°
IN-C33CTOIR	950,960	С	550	600	2.0	2.2	120°
	850-860	D	600	650	2.2	2.4	120°

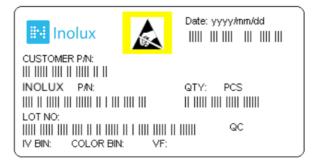
Note:

1. Forward voltage (V_F) ±0.1V, Radiometric Power (Po) ±10%.

2. Testing current of 5W is 1000mA



Label Specifications



Inolux P/N:

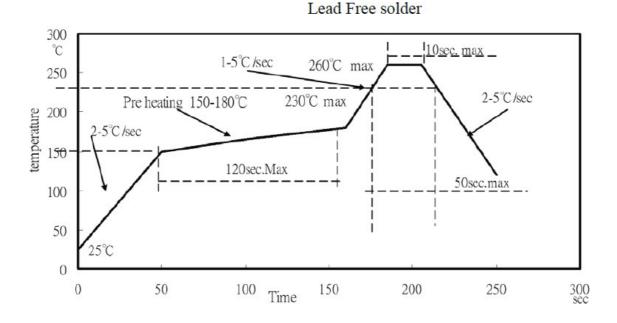
1		Ν	-	С	3	3		Т	0		IR	-	Х	Х	Х	Х
				Material	Pacl	kage	Variation	Orientation	Current	Lens	Color			usto Stam		
	nol SM	ux D		C = Ceramic Type	33B 33C =	= 3.5 x 3 = 3.5 x 3.	9.5, 30 Deg. 1.5, 60 Deg. 5, 120 Deg. 1.5, 90 Deg.	T = Top Mount	O = 1000mA	(Blank) = Clear	IR = 850nm					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker		Year (2017	, 2018,)		Month	Date	Serial



Reflow Soldering



Soldering Iron

Basic Spec is \leq 4 sec. when 260°C (+10°C \rightarrow -1 second). Power dissipation of Iron should be less than 15W. Surface temperature should be under 230°C

Rework

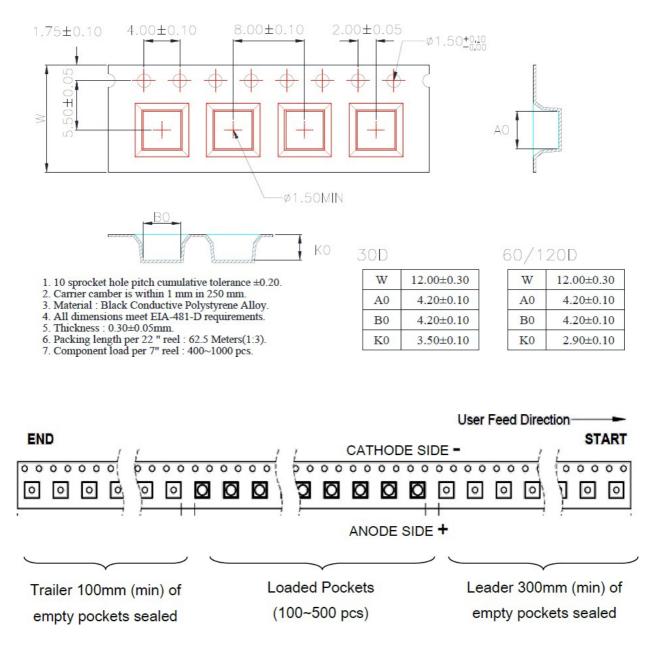
Rework should be completed within 4 second under 245°C

Notes

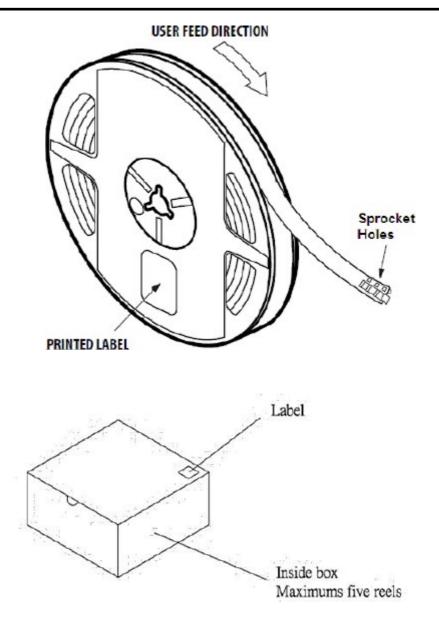
- 1. Do not stress the silicone resin while it is exposed to high temperature.
- 2. The number of reflow process should not exceed 3 times.



Packing







Notes:

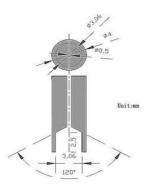
- 1. Each Reel (minimum number of pieces is 100 and maximum is 500 (60D)/1000 (120D) is packed in a moisture-proof bag along with 2 packs of desiccant and a humidity indicator card;
- 2. A maximum of 5 moisture-proof bags are packed in an inner box (size: 240mm x 200mm x 105mm \pm 5mm)
- 3. A maximum of 4 inner boxes are put in an outer box (size: 410mm x 255mm x 230mm \pm 5mm)
- 4. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.



Precautions

- 1. Recommendation for using LEDs
 - 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
 - 1.2 Avoid mechanical stress on LED lens.
 - 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
 - 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging
- 2. Pick & place nozzle

The pickup tool was recommended and shown as below



3. Lens handling

Please follow the guideline to pick LEDs

- 3.1 Use tweezers to pick LEDs
- 3.2 Do not touch the lens by using tweezers
- 3.3 Do not touch lens with fingers
- 3.4 Do not apply more than 4N of lens (400g) directly onto the lens
- 4. Lens cleaning

In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

- 4.1 Try a gentle wiping with dust-free cloth
- 4.2 If needed, use dust-free cloth and isopropyl alcohol to gently clean the dirt from the lens surface.
- 4.3 $\,$ Do not use other solvents as they may directly react with the LED assembly
- 4.4 Do not use ultrasonic cleaning which will damage the LEDs



Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	–40°C 30min ↑↓5min 125°C 30min	100 cycles	0/22	AECQ101
High Temperature Storage	Ta=100°C	1000 hrs	0/22	EIAJ ED-4701 200 201
Humidity Heat Storage	Ta=85℃ RH=85%	1000 hrs	0/22	EIAJ ED-4701 100 103
Low Temperature Storage	Ta=-40°C	1000 hrs	0/22	EIAJ ED-4701 200 202
Life Test	Ta=25℃ If=700mA	1000 hrs	0/22	Tested with IN standard
High Humidity Heat Life Test	85℃ RH=85% If=700mA	1000 hrs	0/22	Tested with IN standard
High Temperature Life Test	Ta=85℃	1000 hrs	0/22	Tested with IN standard
ESD(HBM)	2KV at 1.5kΩ;100pf	3 Times	0/22	MIL-STD-883

Criteria for Judging the Damage								
ltow	Curren e l	Condition	Criteria for Judgment					
ltem	Symbol	Condition	Min	Max				
Forward Voltage	VF	If=700mA	-	$USL^1 \times 1.1$				
Reverse Current	IR	VR =5V	-	100µA				
Luminous Intensity	lv	If=700mA	LSL ² ×0.7	-				

Notes:

- 1. USL: Upper specification level
- 2. LSL: Lower specification level



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	04-16-2018
Spec. Update	5	1.1	12-03-2018
Update the Drawing	4	1.2	05-13-2019

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